



Customer Information Notification **Update**

202202017IU01 : Visual Cosmetic Change to Product Appearance for Various ATKH QFP Packages

Note: This notice is NXP Company Proprietary.

Issue Date: Aug 11, 2022 **Effective date:** Aug 12, 2022

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Management summary

Visual Cosmetic Change to Product Appearance for Various ATKH QFP Packages

Change Category

- Wafer Fab Process
- Assembly Process
- Product Marking
- Test Process
- Design
- Wafer Fab Materials
- Assembly Materials
- Mechanical Specification
- Test Equipment
- Errata
- Wafer Fab Location
- Assembly Location
- Packing/Shipping/Labeling
- Test Location
- Electrical spec./Test coverage
- Firmware
- Other: Change of visual cosmetic appearance of product package

PCN Overview

Description

Our Assembly Site ATKH in Kaohsiung Taiwan is upgrading moulding equipment, which will result in visual cosmetic changes to product appearance for various QFP packages.

Reason

For affected products our Manufacturing Site in Taiwan is upgrading their moulding equipment.

Identification of Affected Products

Changed products can be identified by the added ejector marks and the date code in the final line(s) of the product's top marking. This date code is also shown on packing labelling.

Change over planning is indicated in the type list in the excel file attached to this mail notification

For example change over in wk2212 (wk 12 of 2022) means:

- Products with datecodes up to and including wk2211 will be produced on old equipment
- Products with datecodes wk2212 and later will be produced on new equipment

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Additional documents: [view online](#)

Remarks

Please use the link 'view online' under the heading 'Additional information' above, to log in to the NXP e-PCN system you're subscribed to, in order to obtain the attached document 'Attachment to NXP CIN 202202017I.pdf' with relevant detailed information from the tab 'Files'.

Should you not be able to obtain this document, please contact your NXP sales representative or the e-mail address mentioned below under 'Contact and Support'.

Update Information

Most of the changes communicated via CIN202202017 have already been implemented, but this updated CIN communicates that part of conversion has been cancelled.

For the products in TQFP64, LQFP64, LQFP32 and part of products in HTQFP64 the change will not be introduced.

Please see the attached excel file that describes the status update for each Sales Item.

The reason for this update is that due changes to internal loading, part of the program has been cancelled.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Michiel Maas Geesteranus

Position Assembly Change Coordinator

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NXP Quality Management Team.

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